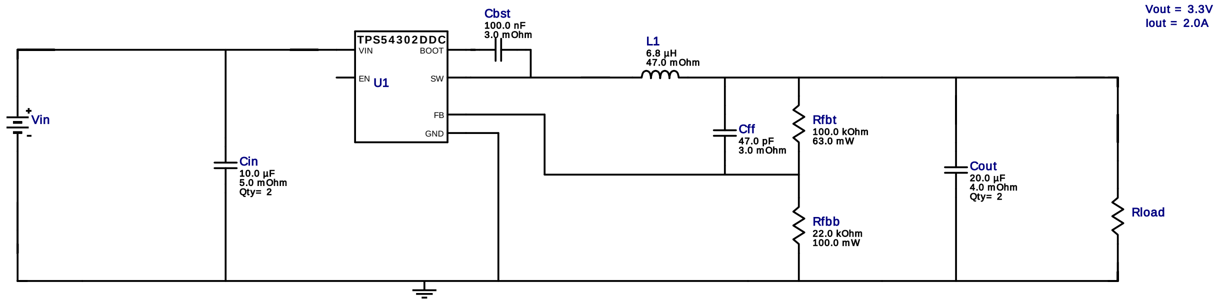
VinMin = 23.0V
VinMax = 25.0V
Vout = 3.3V
Iout = 2.0A

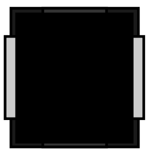
Device = TPS54302DDCR
Topology = Buck
Created = 2023-01-02 19:28:58.791
BOM Cost = NA
BOM Count = 10
Total Pd = 1.03W

WEBENCH ® Design Report

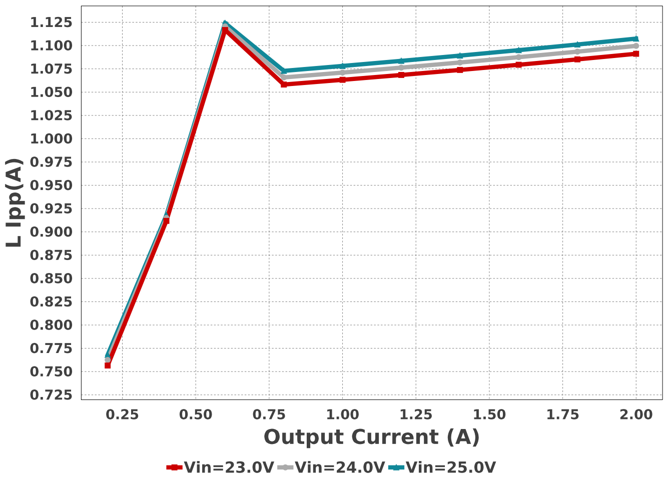
Design : 113 TPS54302DDCR
TPS54302DDCR 23V-25V to 3.30V @ 2A



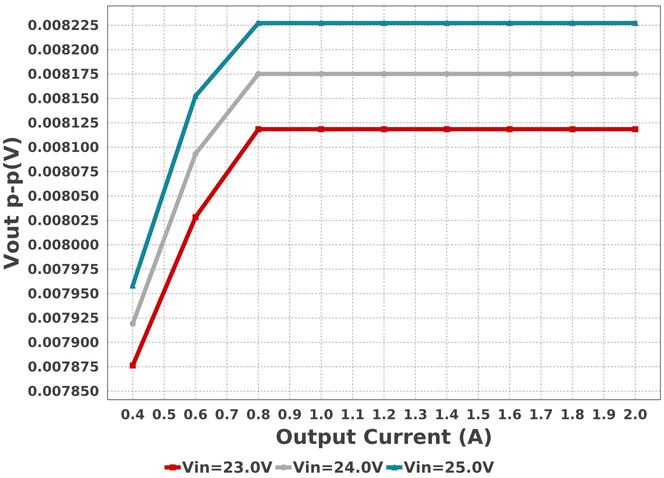
Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cbst	CUSTOM	CUSTOM Series= X7R	Cap= 100.0 nF ESR= 3.0 mOhm VDC= 50.0 V IRMS= 1.64 A	1	NA	0805 0 mm²
Cff	CUSTOM	CUSTOM Series= C0G/NP0	Cap= 47.0 pF ESR= 3.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	NA	0201 0 mm²
Cin	Samsung Electro-Mechanics	CL32B106KBJNNWE Series= X7R	Cap= 10.0 uF ESR= 5.0 mOhm VDC= 50.0 V IRMS= 0.0 A	2	$0.17	1210_270 15 mm²
Cout	CUSTOM	CUSTOM Series= X7R	Cap= 20.0 uF ESR= 4.0 mOhm VDC= 25.0 V IRMS= 0.0 A	2	NA	1210_270 0 mm²
L1	CUSTOM	CUSTOM	L= 6.8 µH 47.0 mOhm	1	NA	 HC1 0 mm²
Rfbb	Yageo	RC0603FR-0722KL Series= ?	Res= 22.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	$0.01	0603 5 mm²
Rfbt	Vishay-Dale	CRCW0402100KFKED Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
U1	Texas Instruments	TPS54302DDCR	Switcher	1	$0.55	DDC0006A_N 10 mm²

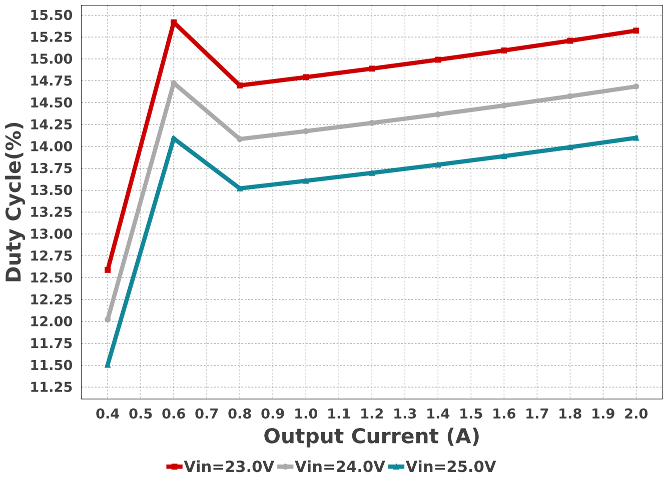
L Ipp



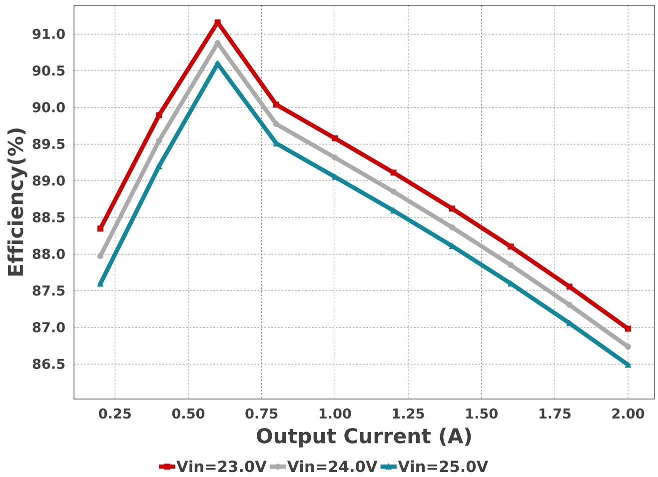
Vout p-p



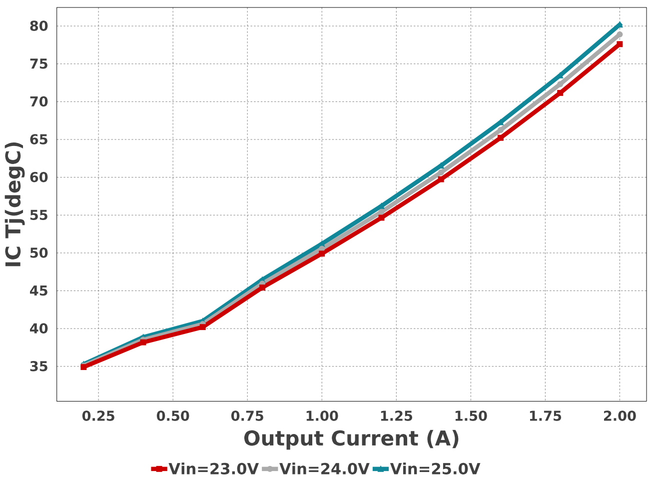
Duty Cycle



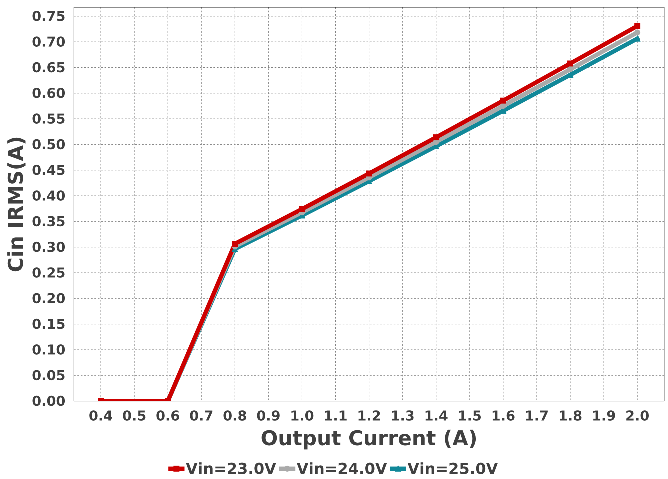
Efficiency

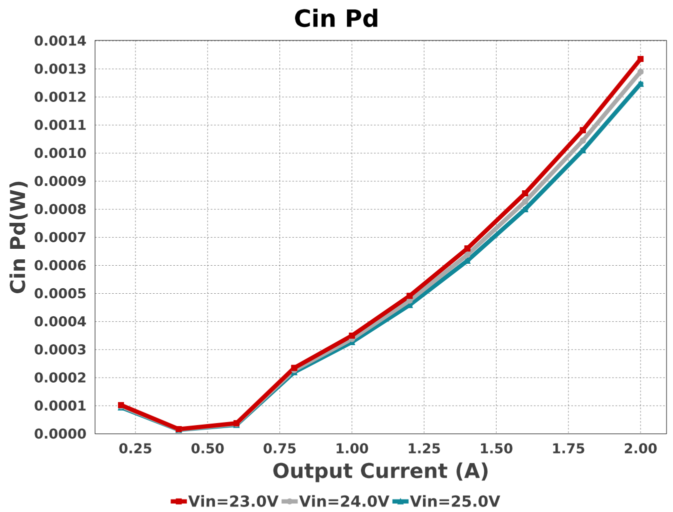


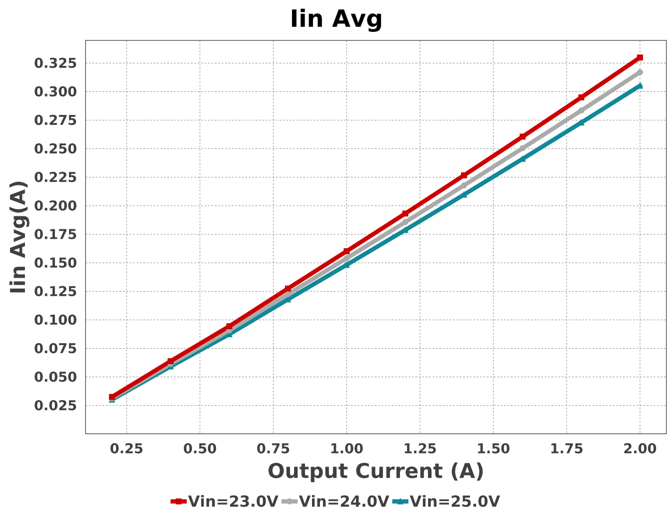
IC Tj

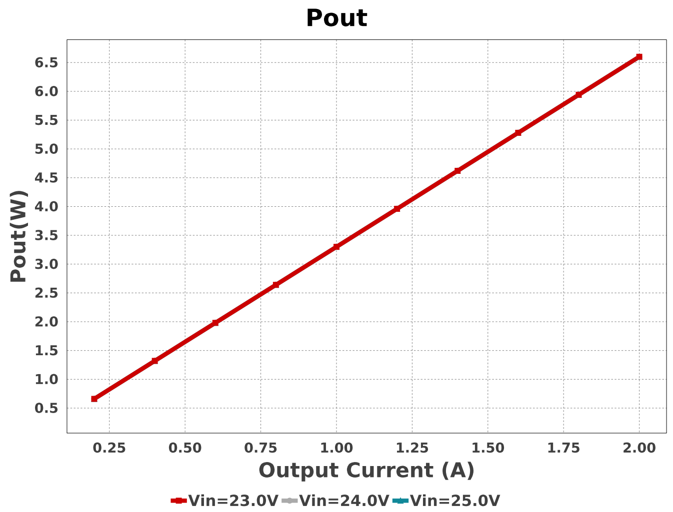


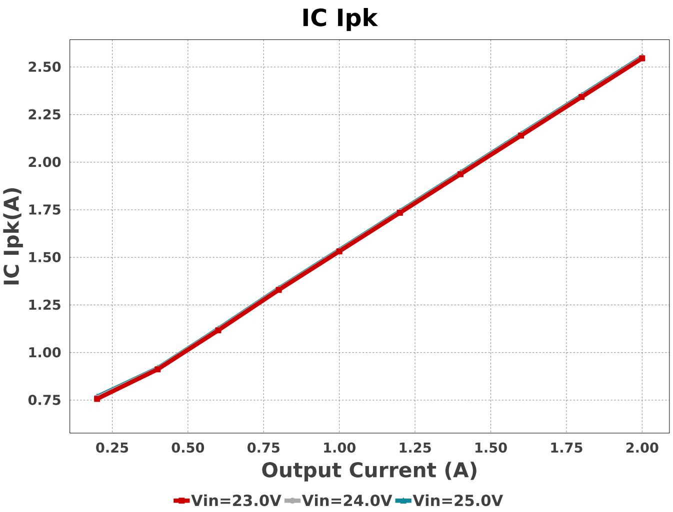
Cin IRMS

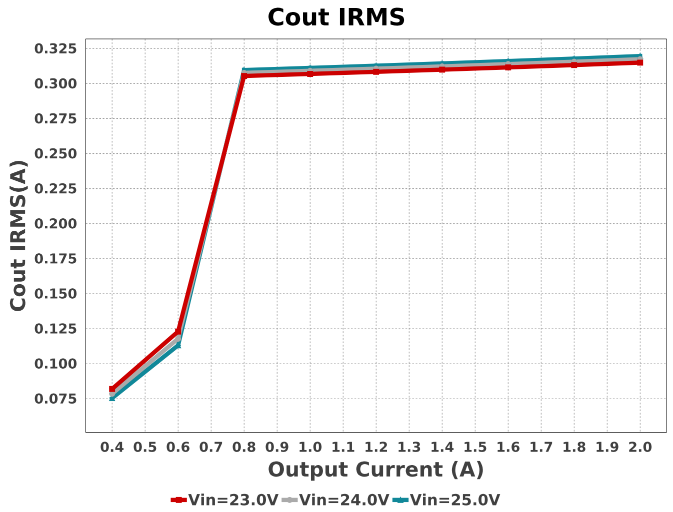


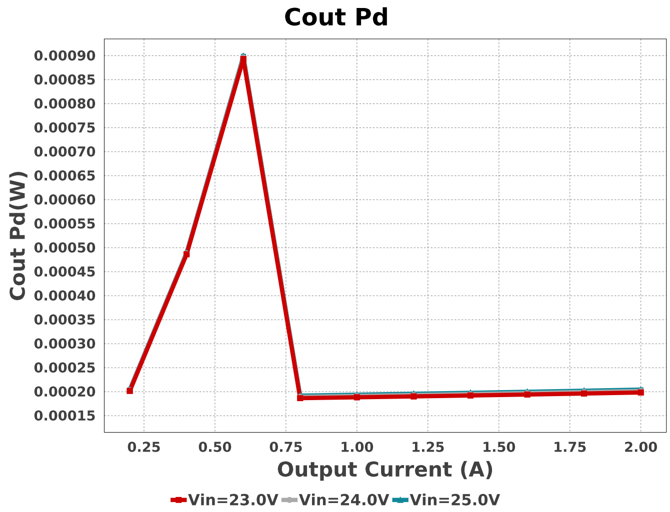

Cin Pd
Cin Pd(W)
Output Current (A)
Vin=23.0V Vin=24.0V Vin=25.0V

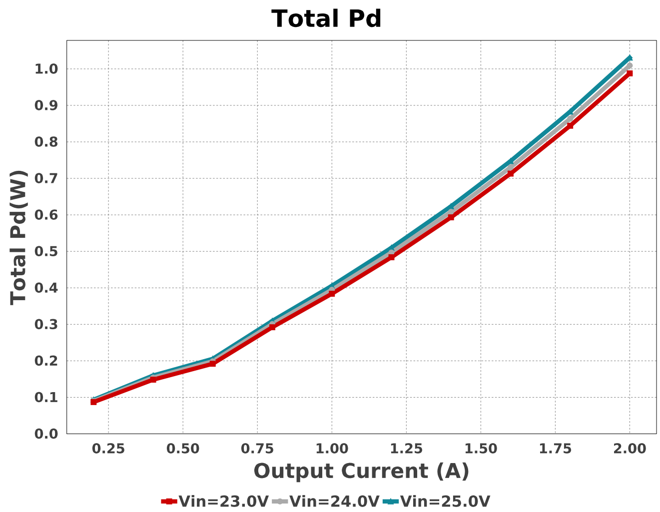

Iin Avg
Iin Avg(A)
Output Current (A)
Vin=23.0V Vin=24.0V Vin=25.0V

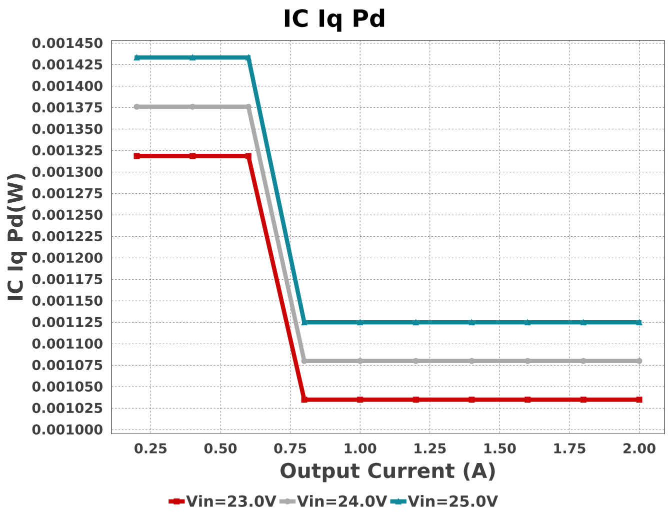

Pout
Pout(W)
Output Current (A)
Vin=23.0V Vin=24.0V Vin=25.0V

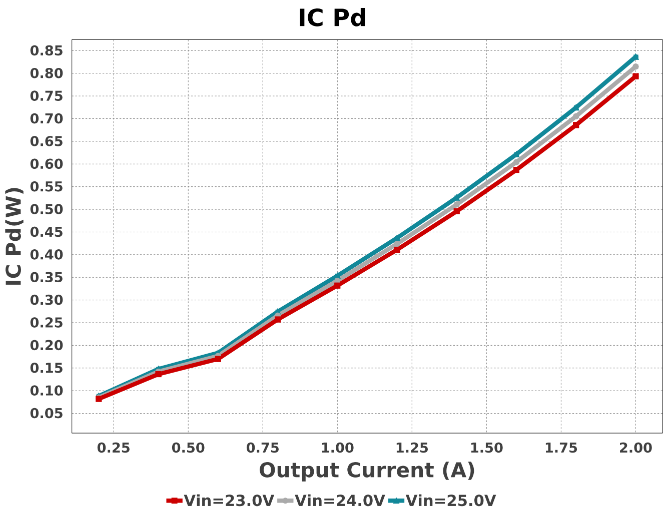

IC Ipk
IC Ipk(A)
Output Current (A)
Vin=23.0V Vin=24.0V Vin=25.0V

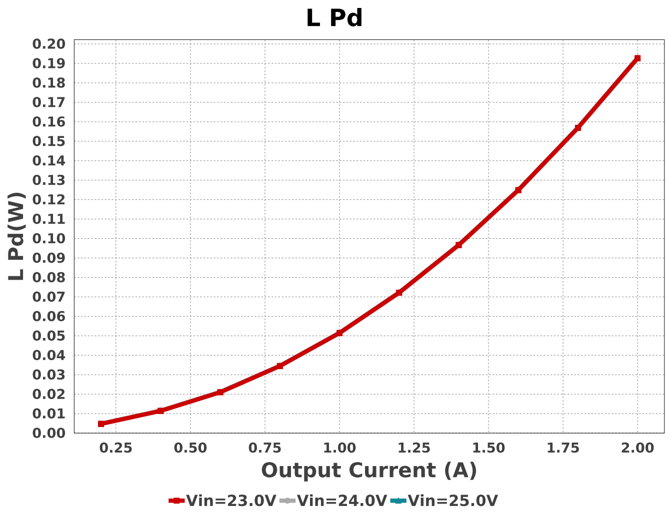

Cout IRMS
Cout IRMS(A)
Output Current (A)
Vin=23.0V Vin=24.0V Vin=25.0V

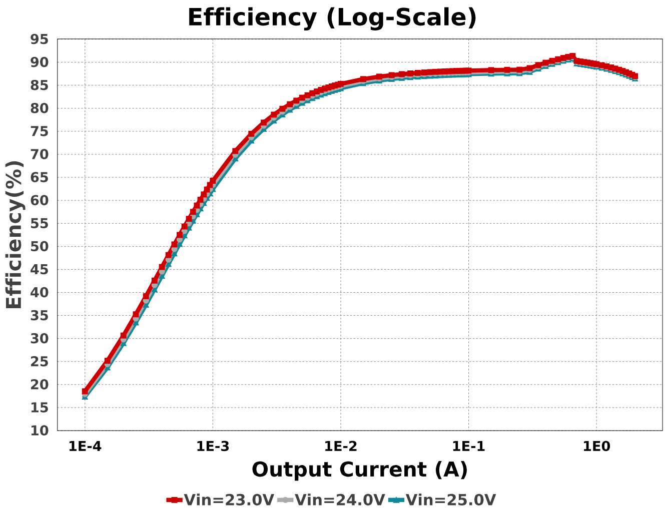

Cout Pd
Cout Pd(W)
Output Current (A)
Vin=23.0V Vin=24.0V Vin=25.0V











Operating Values

#	Name	Value	Category	Description
1.	BOM Count	10		Total Design BOM count
2.	Total BOM	NA		Total BOM Cost
3.	Cin IRMS	706.293 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	1.247 mW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	319.697 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	204.41 µW	Capacitor	Output capacitor power dissipation
7.	IC Ipk	2.554 A	IC	Peak switch current in IC
8.	IC Iq Pd	1.125 mW	IC	IC Iq Pd
9.	IC Pd	836.49 mW	IC	IC power dissipation
10.	IC Tj	80.189 degC	IC	IC junction temperature
11.	ICThetaJA Effective	60.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance

#	Name	Value	Category	Description
12.	Iin Avg	305.23 mA	IC	Average input current
13.	L Ipp	1.107 A	Inductor	Peak-to-peak inductor ripple current
14.	L Pd	192.8 mW	Inductor	Inductor power dissipation
15.	Cin Pd	1.247 mW	Power	Input capacitor power dissipation
16.	Cout Pd	204.41 µW	Power	Output capacitor power dissipation
17.	IC Pd	836.49 mW	Power	IC power dissipation
18.	L Pd	192.8 mW	Power	Inductor power dissipation
19.	Total Pd	1.031 W	Power	Total Power Dissipation
20.	Duty Cycle	14.099 %	System Information	Duty cycle
21.	Efficiency	86.491 %	System Information	Steady state efficiency
22.	FootPrint	311.0 mm^2	System Information	Total Foot Print Area of BOM components
23.	Frequency	400.0 kHz	System Information	Switching frequency
24.	Iout	2.0 A	System Information	Iout operating point
25.	Mode	CCM	System Information	PWM/PFM Mode
26.	Pout	6.6 W	System Information	Total output power
27.	Vin	25.0 V	System Information	Vin operating point
28.	Vout Actual	3.305 V	System Information	Vout Actual calculated based on selected voltage divider resistors
29.	Vout Tolerance	1.656 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
30.	Vout p-p	8.227 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	2.0	Maximum Output Current
VinMax	25.0	Maximum input voltage
VinMin	23.0	Minimum input voltage
VinTyp	24.0	Typical input voltage
Vout	3.3	Output Voltage
base_pn	TPS54302	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

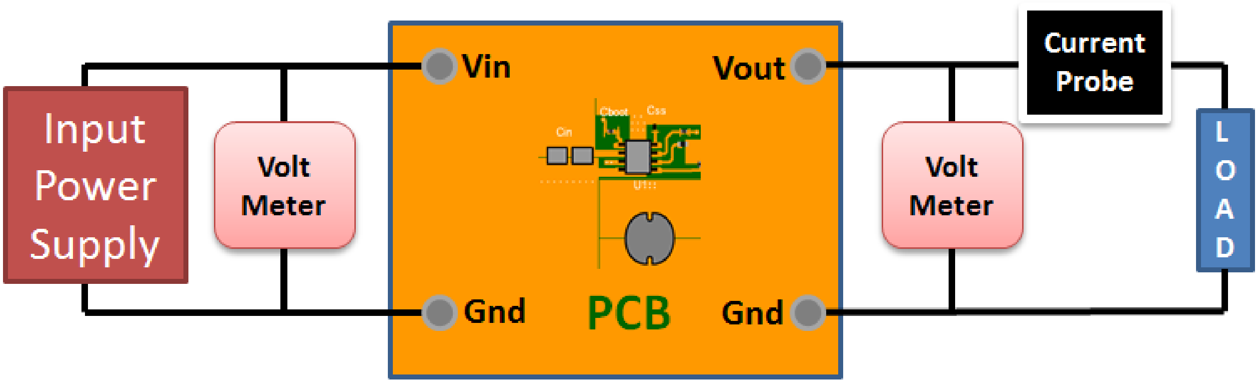
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 23.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

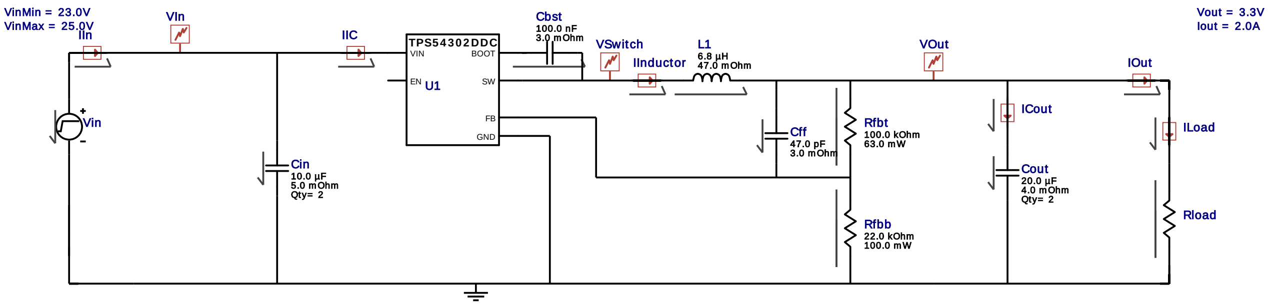


WEBENCH® Electrical Simulation Report

Design Id = 113

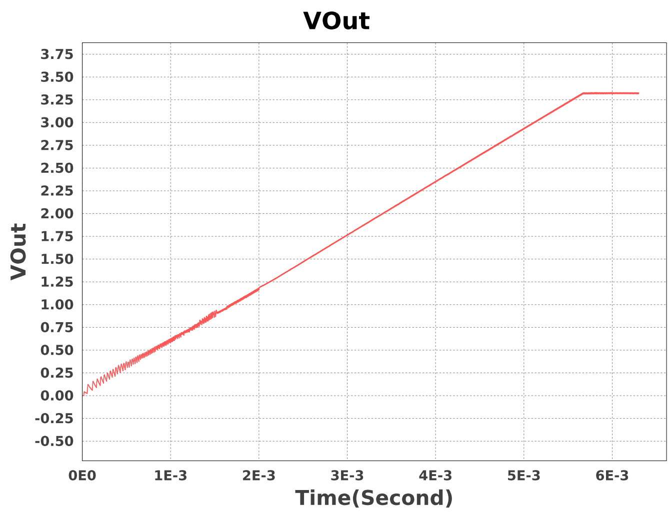
sim_id = 1

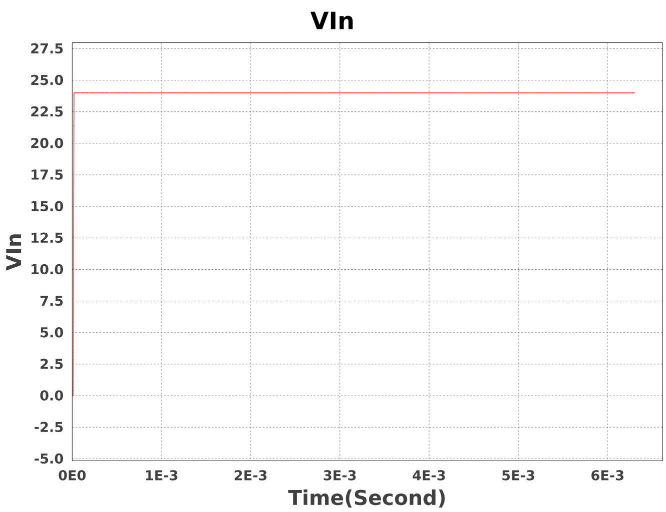
Simulation Type = Startup



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Rload	R	Load Resistance	1.65 Ohm

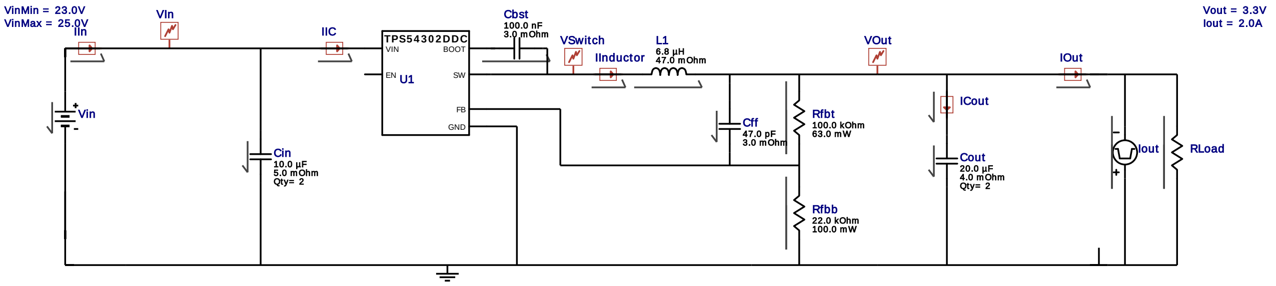




Design Id = 113

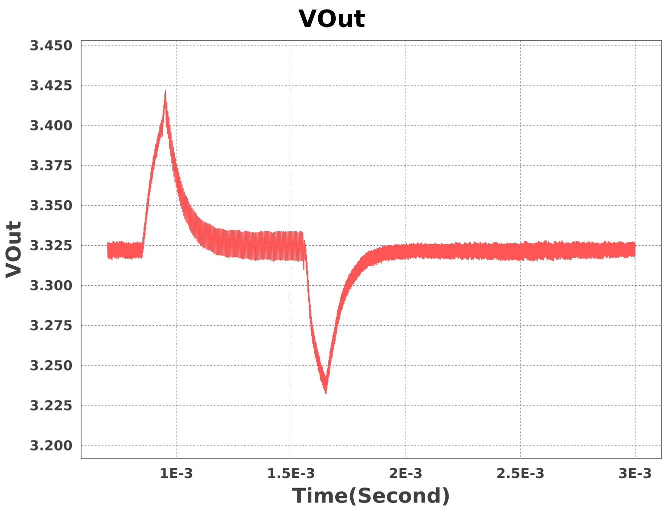
sim_id = 2

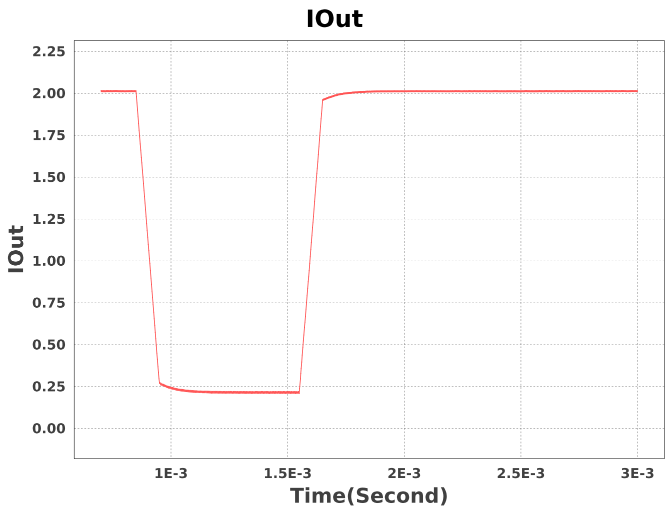
Simulation Type = Load Transient



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	L1	IC	Initial Current	-2.0 V
2.	Cbst	IC	Initial Voltage	23.0 V
3.	Iout	signal_type I1 I2 Td Tf Tr Pw	Signal Type Initial Load Current Minimum Load Current Initial Time Delay Fall Time Rise Time Pulse Width	PULSE 0 A 1.8 A 850u s 100u s 100u s 600u s
4.	RLoad	R	Load Resistance	1.65 Ohm

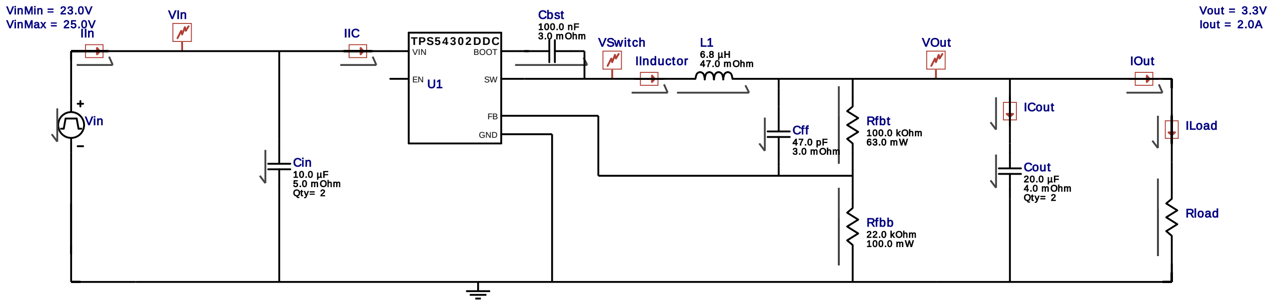




Design Id = 113

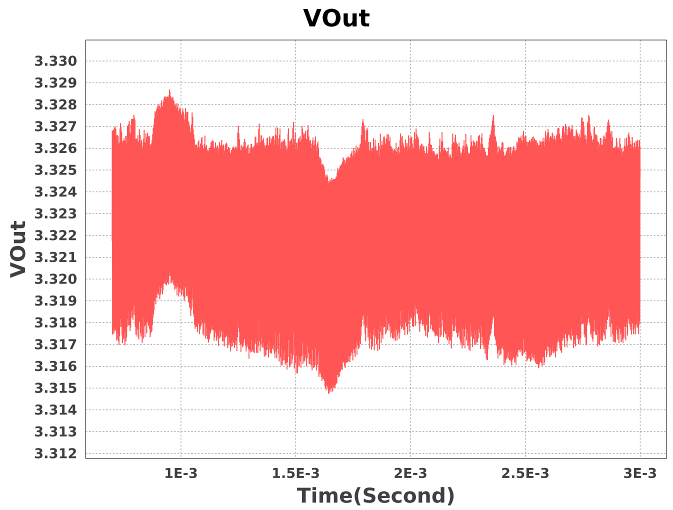
sim_id = 3

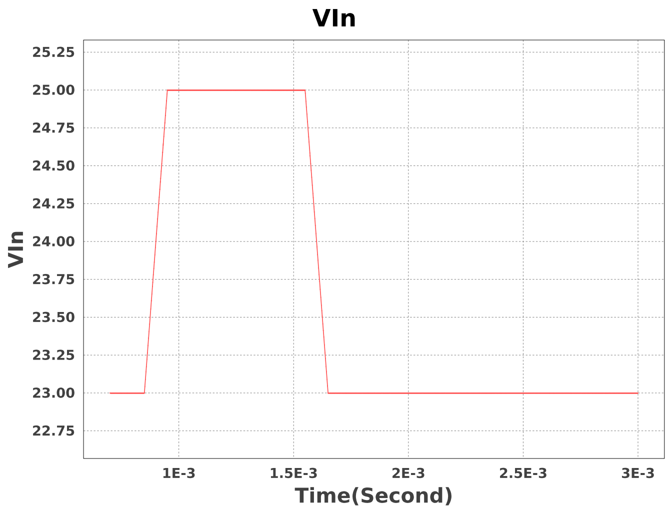
Simulation Type = Input Transient



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	L1	IC	Initial Current	-2.0 V
2.	Cbst	IC	Initial Voltage	23.0 V
3.	Rload	R	Load Resistance	1.65 Ohm

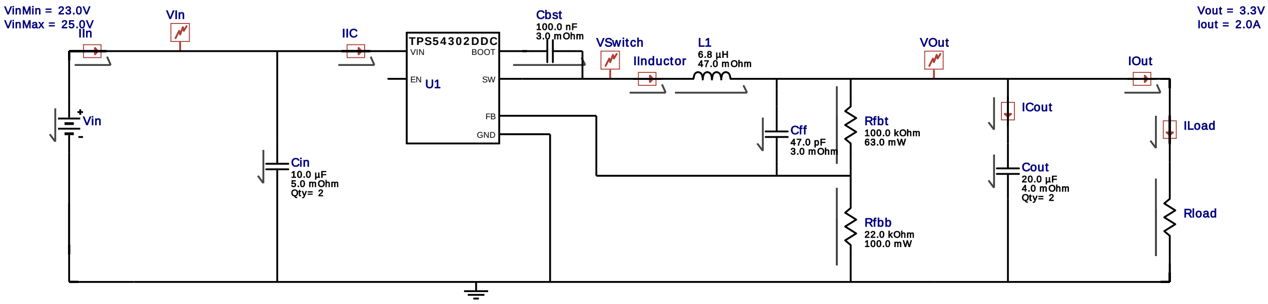




Design Id = 113

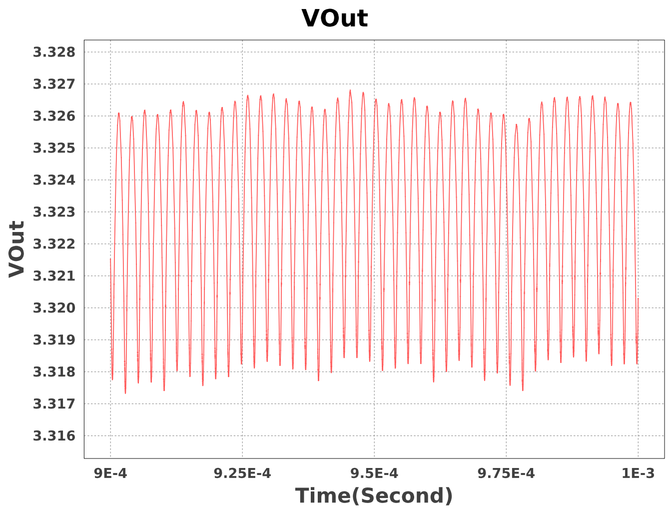
sim_id = 4

Simulation Type = Steady State



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	L1	IC	Initial Current	-2.0 V
2.	Cbst	IC	Initial Voltage	23.0 V
3.	Rload	R	Load Resistance	1.65 Ohm



Design Assistance

1. Master key : BED2B438EB35597A[v1]

2. **TPS54302** Product Folder : http://www.ti.com/product/TPS54302 : contains the data sheet and other resources.